L Number	Hits	Search Text	DB	Time stamp
1	662	(driver with substrate) same lcd	USPAT;	2004/08/06 12:56
	552	,	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
2	7	((driver with substrate) same lcd) and	USPAT;	2004/08/06 13:00
		349/158	US-PGPUB;	
			EPO; JPO;	
			DERWENT	0001/00/05 10 05
3	32	((driver with substrate) same lcd) and (flip	USPAT;	2004/08/06 13:05
		with chip)	US-PGPUB;	
			EPO; JPO; DERWENT	
	7101	banding add area	USPAT;	2004/08/06 13:38
4	7121	bonding adj area	US-PGPUB;	2004/00/00 13:30
			EPO; JPO;	
			DERWENT	
5	11822	(bonding adj area) and (349/). ccls	USPAT;	2004/08/06 13:08
,	11022	(bonding day died, and (313,), cold	US-PGPUB;	2000,000,000
			EPO; JPO;	
1			DERWENT	
6	8	(bonding adj area) and 349/151	USPAT;	2004/08/06 13:38
-			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
7	7	(bonding adj area) and 349/152	USPAT;	2004/08/06 13:21
			US-PGPUB;	
			EPO; JPO;	
		l	DERWENT	, ,
8	8	(bonding adj area) and 349/151	USPAT;	2004/08/06 13:22
			US-PGPUB;	
			EPO; JPO;	
		(h	DERWENT	2004/08/06 13:45
9	13	(bonding adj area) and 349/150	USPAT; US-PGPUB;	2004/08/06 13:45
			EPO; JPO;	
			DERWENT	
10	16	(bonding adj area) and 349/149	USPAT;	2004/08/06 13:26
10	10	(Soliding adjusted, and 500, 400	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
11	1	(bonding adj area) same (driver adj chip)	USPAT;	2004/08/06 13:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	0004/00/00 50 15
12	24	(bonding adj area) and (driver adj chip)	USPAT;	2004/08/06 13:40
			US-PGPUB;	
			EPO; JPO;	
13	5	(bonding adj area) and 349/158	DERWENT USPAT;	2004/08/06 13:48
13	5	(boliding adj atea) and 349/130	US-PGPUB;	2504/00/00 15.40
			EPO; JPO;	
			DERWENT	
14	3	(bonding adj area) and 349/139	USPAT;	2004/08/06 13:53
		(12	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
15	2	(bonding adj area) and 349/84	USPAT;	2004/08/06 13:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
16	4	(bonding adj area) and 349/187	USPAT;	2004/08/06 13:54
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	

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